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Title:Low noise amplification at 0.67 THz using 30 nm InP HEMTs Authors: Deal, William R. (1); Leong, K. (1); Radisic, V. (1); Sarkozy, S. (1); Gorospe, B. (1); Lee, J. (1); Liu, P.H. (1); Yoshida, W. (1); Zhou, J. (1); Lange, M. (1); Lai, R. (1); Mei, X.B. (1) Author affiliation:(1) Northrop Grumman Corporation, Redondo Beach, CA 90278, United States Corresponding author: Deal, W.R. (william.deal@ngc.com) Source title: IEEE Microwave and Wireless Components Letters Abbreviated source title:IEEE Microwave Compon. Lett. Volume:21 Issue:7 Issue date:July 2011 Publication year:2011 Pages:368-370 Article number: 5784355 Language:English ISSN:15311309 CODEN:IMWCBJ Document type: Journal article (JA) Publisher:Institute of Electrical and Electronics Engineers Inc., 445 Hoes Lane / P.O. Box 1331, Piscataway, NJ 08855-1331, United States Abstract: In this letter, low noise amplification at 0.67 THz is demonstrated for the first time. A

Abstract: In this letter, low holse amplification at 0.67 THZ is demonstrated for the first time. A packaged InP High Electron Mobility Transistor (HEMT) amplifier is reported to achieve a noise figure of 13 dB with an associated gain greater than 7 dB at 670 GHz using a high fMAX InP HEMT transistors in a 5 stage coplanar waveguide integrated circuit. A 10-stage version is also reported to reach a peak gain of 30 dB. These results indicate that InP HEMT integrated circuits can be useful at frequencies approaching a terahertz.

Number of references:7